

Description

The PMV250EPEAR-JSM uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOT-23

General Features

$V_{DS} = -40V$ $I_D = -5.0A$

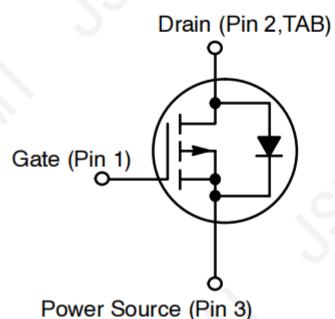
$R_{DS(ON)} < 70m\Omega$ @ $V_{GS} = -10V$

Application

Battery protection

Load switch

Uninterruptible power supply



Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

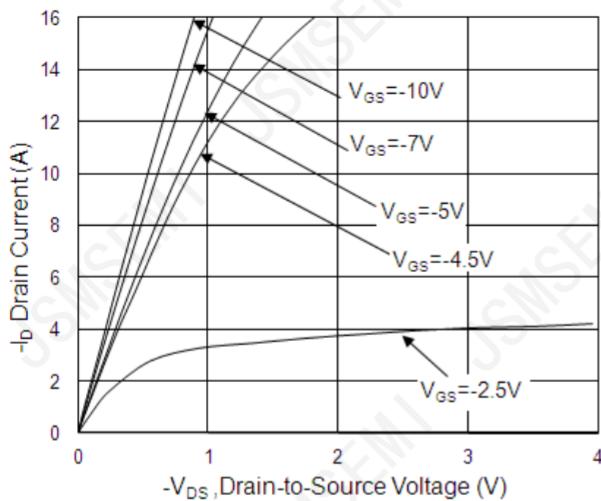
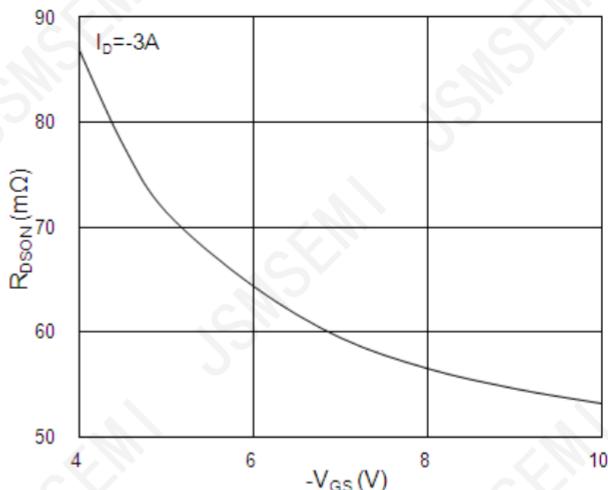
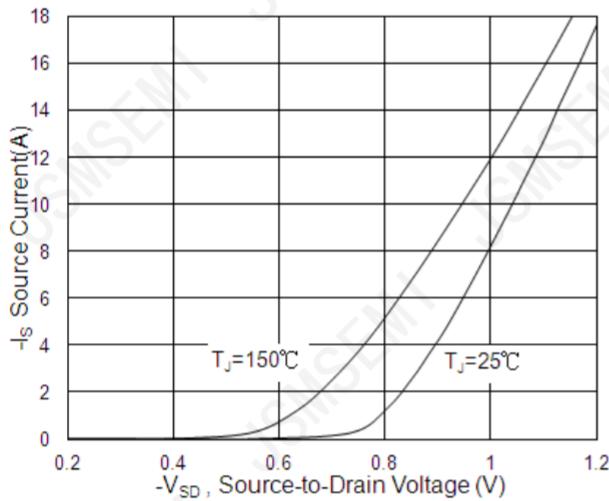
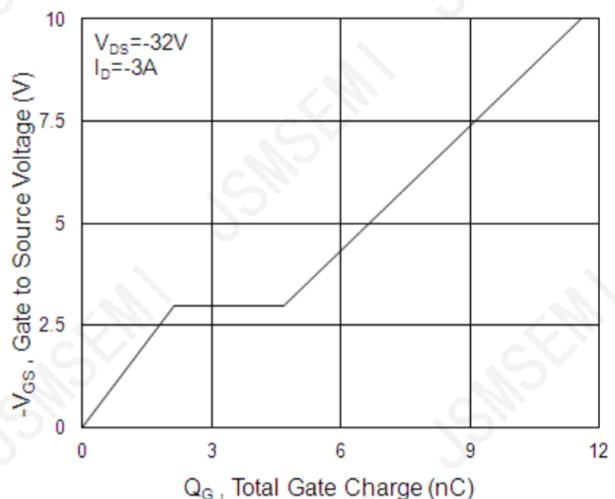
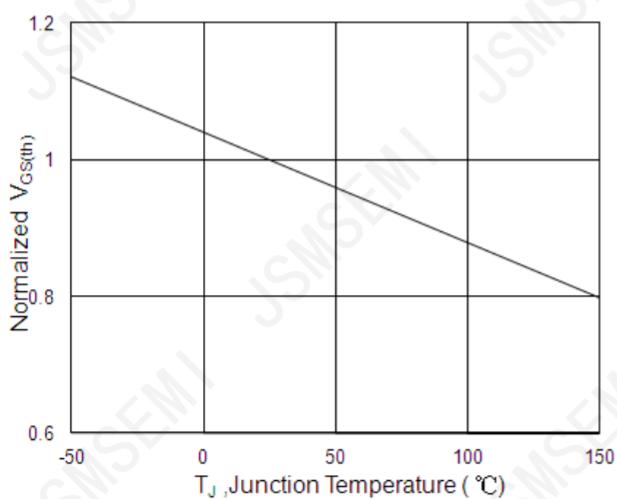
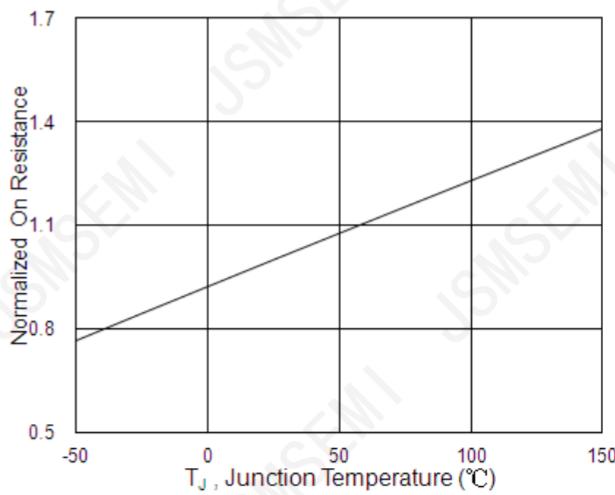
Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-5	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.8	A
I_{DM}	Pulsed Drain Current ²	-18	A
EAS	Single Pulse Avalanche Energy ³	21	mJ
I_{AS}	Avalanche Current	-20.5	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	85	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	50	$^\circ C/W$

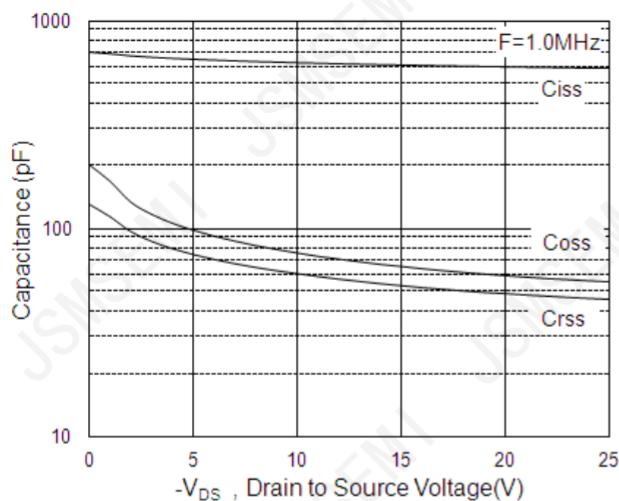
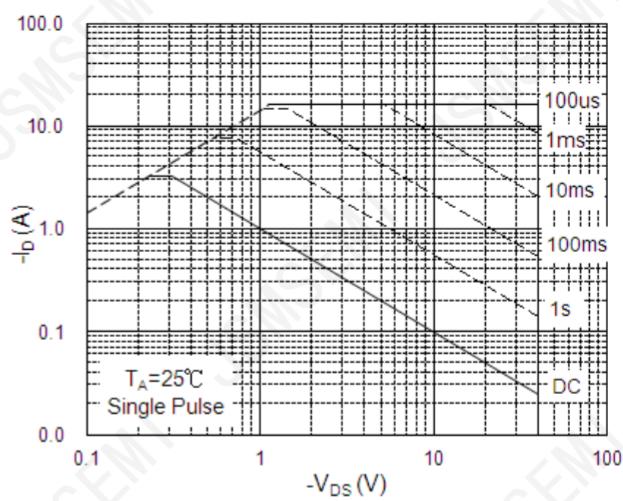
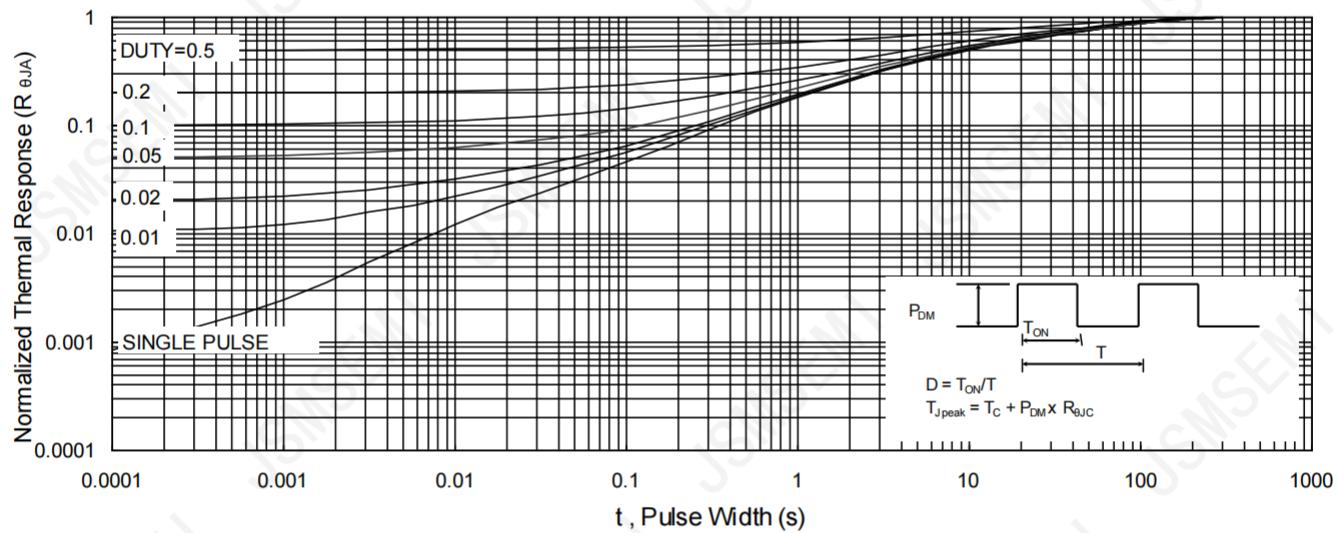
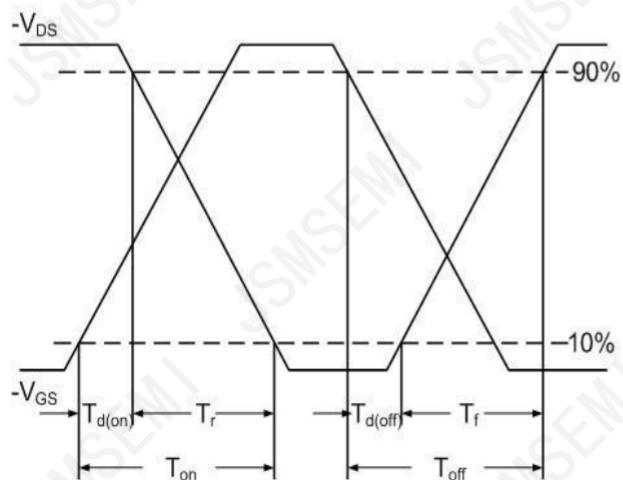
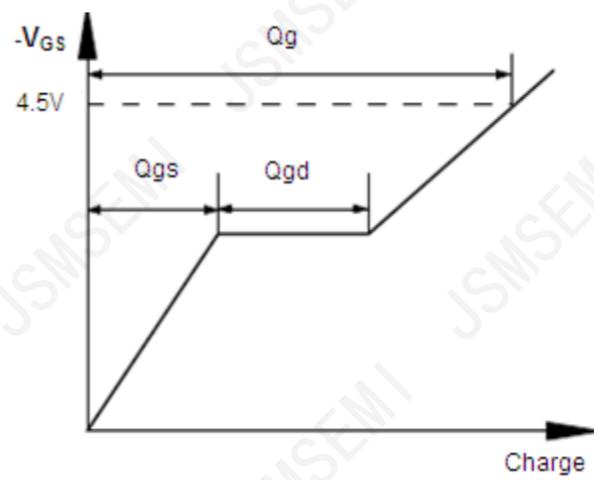
Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-40	-46	---	V
△BVDSS/△T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.018	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-3A	---	65	70	mΩ
		V _{GS} =-4.5V, I _D =-2A	---	85	100	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.5	-2.5	V
△V _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	2.5	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =55°C	---	---	-5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-3A	---	5.8	---	S
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-32V, V _{GS} =-4.5V, I _D =-3A	---	6.4	---	nC
Q _{gs}	Gate-Source Charge		---	2.1	---	
Q _{gd}	Gate-Drain Charge		---	2.5	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-20V, V _{GS} =-4.5V, R _G =3.3Ω, I _D =-3A	---	4.2	---	ns
T _r	Rise Time		---	23	---	
T _{d(off)}	Turn-Off Delay Time		---	26.8	---	
T _f	Fall Time		---	20.6	---	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	620	---	pF
C _{oss}	Output Capacitance		---	65	---	
C _{rss}	Reverse Transfer Capacitance		---	53	---	
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	-3.2	A
I _{SM}	Pulsed Source Current ^{2,4}		---	---	-16.1	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1	V

Note :

1. The data tested by surface mounted on a 1 inch FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. G-S Voltage

Fig.3 Forward Characteristics Of Reverse

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized V_GS(th) vs. T_J

Fig.6 Normalized R_DSON vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

Revision History

Rev.	Change	Date
V1.0	Initial version	2/23/2024

Important Notice

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